

Title (en)

METHOD FOR DISSIPATING HEAT FROM ELECTRONIC COMPONENTS FOR THE OPERATION OF A LIQUID PUMP

Title (de)

VERFAHREN ZUR WÄRMEABFUHR VON ELEKTRONISCHEN BAUTEILEN ZUM BETRIEB EINER FLÜSSIGKEITSPUMPE

Title (fr)

PROCÉDÉ POUR DISSIPER DE LA CHALEUR À PARTIR DE COMPOSANTS ÉLECTRONIQUES, AFIN D'ACTIONNER UNE POMPE À LIQUIDES

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Application

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Abstract (en)

[origin: WO2009000601A1] The invention relates to a method in which the electronic components (2) are contacted with a carrier (1) consisting of metallic materials and which consists of a flow pipe (1a) which is integrated in the supply line or in the discharge line for the liquid pump (3) and which, on the outer side thereof, has a plate-shaped element (1b) for contacting the electronic components (2). The heat is dissipated from the electronic components (2) over the plate-shaped element (1b) and the flow pipe (1a) of the carrier (1) into the liquid inflowing medium. A further object of the invention is a device for implementing the method, and the use of the device as a cooling device for cooling electronic components (2) for the operation of a cooling water pump in a motor vehicle.

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